What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.
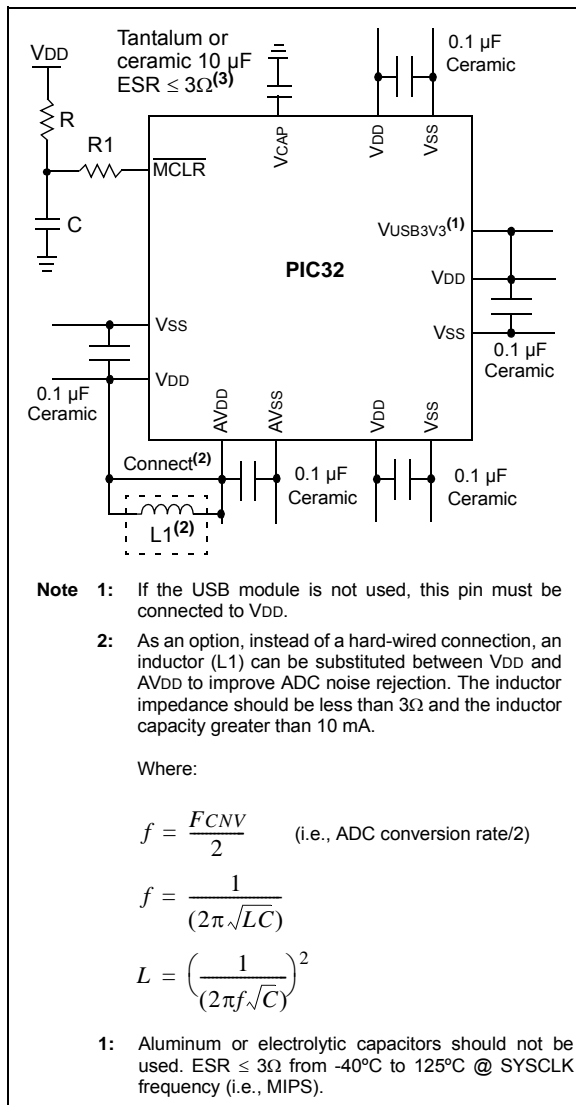
Applications of "[Embedded - Microcontrollers](#)"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f128h-i-mr

FIGURE 2-1: **RECOMMENDED MINIMUM CONNECTION**

Note 1: If the USB module is not used, this pin must be connected to V_{DD}.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between V_{DD} and AV_{DD} to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC conversion rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR $\leq 3\Omega$ from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (V_{CAP})

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the V_{CAP} pin, which is used to stabilize the internal voltage regulator output. The V_{CAP} pin must not be connected to V_{DD}, and must have a C_{EFC} capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **Section 31.0 "Electrical Characteristics"** for additional information on C_{EFC} specifications.

2.4 Master Clear ($\overline{MCLR}$) Pin

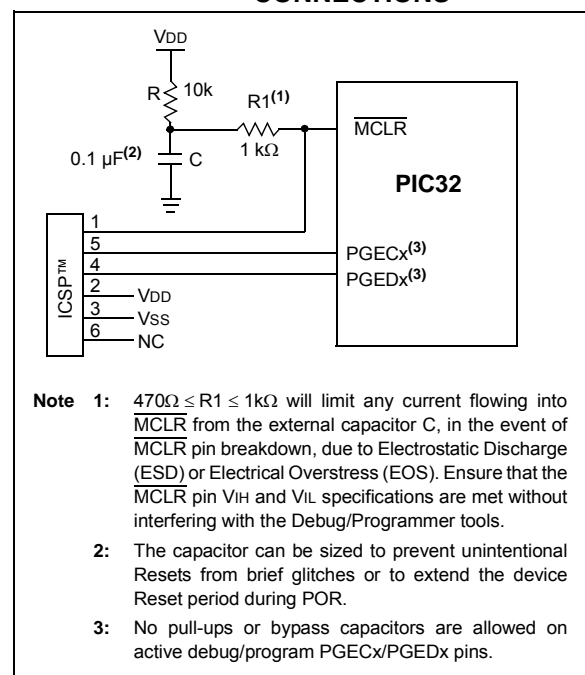The $\overline{MCLR}$ pin provides two specific device functions:

- Device Reset
- Device programming and debugging

Pulling The $\overline{MCLR}$ pin low generates a device Reset. Figure 2-2 illustrates a typical $\overline{MCLR}$ circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{MCLR}$ pin.

FIGURE 2-2: **EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS**

Note 1: $470\Omega \leq R1 \leq 1k\Omega$ will limit any current flowing into $\overline{MCLR}$ from the external capacitor C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

PIC32MX330/350/370/430/450/470

3.2 Architecture Overview

The MIPS32® M4K® processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32® M4K® processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. One additional register file shadow set (containing thirty-two registers) is added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the CLZ and CLO instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32® M4K® processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt*) operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent MDU instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/ DIVIDE UNIT LATENCIES AND REPEAT RATES

Op code	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
MULT/MULTU, MADD/MADDU, MSUB/MSUBU	16 bits	1	1
	32 bits	2	2
MUL	16 bits	2	1
	32 bits	3	2
DIV/DIVU	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

4.2 Bus Matrix Registers

TABLE 4-2:   BUS MATRIX REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
2000	BMXCON(1)	31:16	—	—	—	—	—	BMXCHEDMA	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	041F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0047
2010	BMXDKPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMXDUDBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMXDUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMXDRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMXPUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMXPFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMXBOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note   1:   This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 11-4: **U1OTGCON: USB OTG CONTROL REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	DPPULUP	DMPULUP	DPPULDWN	DMPULDWN	VBUSON	OTGEN	VBUSCHG	VBUSDIS

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **DPPULUP:** D+ Pull-Up Enable bit

1 = D+ data line pull-up resistor is enabled
0 = D+ data line pull-up resistor is disabled

bit 6 **DMPULUP:** D- Pull-Up Enable bit

1 = D- data line pull-up resistor is enabled
0 = D- data line pull-up resistor is disabled

bit 5 **DPPULDWN:** D+ Pull-Down Enable bit

1 = D+ data line pull-down resistor is enabled
0 = D+ data line pull-down resistor is disabled

bit 4 **DMPULDWN:** D- Pull-Down Enable bit

1 = D- data line pull-down resistor is enabled
0 = D- data line pull-down resistor is disabled

bit 3 **VBUSON:** VBUS Power-on bit

1 = VBUS line is powered
0 = VBUS line is not powered

bit 2 **OTGEN:** OTG Functionality Enable bit

1 = DPPULUP, DMPULUP, DPPULDWN and DMPULDWN bits are under software control
0 = DPPULUP, DMPULUP, DPPULDWN and DMPULDWN bits are under USB hardware control

bit 1 **VBUSCHG:** VBUS Charge Enable bit

1 = VBUS line is charged through a pull-up resistor
0 = VBUS line is not charged through a resistor

bit 0 **VBUSDIS:** VBUS Discharge Enable bit

1 = VBUS line is discharged through a pull-down resistor
0 = VBUS line is not discharged through a resistor

PIC32MX330/350/370/430/450/470

12.1 Parallel I/O (PIO) Ports

All port pins have ten registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

12.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the presence of outputs higher than VDD (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Device Pin Tables"** section for the available pins and their functionality.

12.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

12.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be an NOP.

12.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX330/350/370/430/450/470 devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and every I/O pin has a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

> **Note:** Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output. They should also be disabled on 5V tolerant pins when the pin voltage can exceed VDD.

An additional control register (CNCONx) is shown in Register 12-3.

12.2 CLR, SET, and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

TABLE 12-7: PORTD REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, PIC32MX370F512L, PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY

Virtual Address (BF88_#)	Register Name[1]	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6300	ANSELD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	ANSELD3	ANSELD2	ANSELD1	—	000E
6310	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISD15	TRISD14	TRISD13	TRISD12	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	xxxx
5320	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RD15	RD14	RD13	RD12	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
6330	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATD15	LATD14	LATD13	LATD12	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
6340	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCD15	ODCD14	ODCD13	ODCD12	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	xxxx
6350	CNPUD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUD15	CNPUD14	CNPUD13	CNPUD12	CNPUD11	CNPUD10	CNPUD9	CNPUD8	CNPUD7	CNPUD6	CNPUD5	CNPUD4	CNPUD3	CNPUD2	CNPUD1	CNPUD0	xxxx
6360	CNPDD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDD15	CNPDD14	CNPDD13	CNPDD12	CNPDD11	CNPDD10	CNPDD9	CNPDD8	CNPDD7	CNPDD6	CNPDD5	CNPDD4	CNPDD3	CNPDD2	CNPDD1	CNPDD0	xxxx
6370	CNCOND	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6380	CNEND	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIED15	CNIED14	CNIED13	CNIED12	CNIED11	CNIED10	CNIED9	CNIED8	CNIED7	CNIED6	CNIED5	CNIED4	CNIED3	CNIED2	CNIED1	CNIED0	xxxx
6390	CNSTATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNSTATD15	CNSTATD14	CNSTATD13	CNSTATD12	CNSTATD11	CNSTATD10	CNSTATD9	CNSTATD8	CNSTATD7	CNSTATD6	CNSTATD5	CNSTATD4	CNSTATD3	CNSTATD2	CNSTATD1	CNSTATD0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.
Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

PIC32MX330/350/370/430/450/470

TABLE 12-12:   PORTF REGISTER MAP FOR PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY

Virtual Address (BF88_#)	Register Name[1]	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6510	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TRISF13	TRISF12	—	—	—	TRISF8	—	—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	xxxx
6520	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	RF13	RF12	—	—	—	RF8	—	—	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6530	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	LATF13	LATF12	—	—	—	LATF8	—	—	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6540	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	ODCF13	ODCF12	—	—	—	ODCF8	—	—	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	xxxx
6550	CNPUF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNPUF13	CNPUF12	—	—	—	CNPUF8	—	—	CNPUF5	CNPUF4	CNPDF3	CNPUF2	CNPUF1	CNPUF0	xxxx
6560	CNPDF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNPDF13	CNPDF12	—	—	—	CNPDF8	—	—	CNPDF5	CNPFF4	CNPDF3	CNPDF2	CNPDF1	CNPDF0	xxxx
6570	CNCONF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6580	CNENF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNIEF13	CNIEF12	—	—	—	CNIEF8	—	—	CNIEF5	CNIEF4	CNIEF3	CNIEF2	CNIEF1	CNIEF0	xxxx
6590	CNSTATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	CNSTATF13	CNSTATF12	—	—	—	CNSTATF8	—	—	CNSTATF5	CNSTATF4	CNSTATF3	CNSTATF2	CNSTATF1	CNSTATF0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.
Note   1:   All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 15-1: **WDTCON: WATCHDOG TIMER CONTROL REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON[1,2]	—	—	—	—	—	—	—
7:0	U-0	R-y	R-y	R-y	R-y	R-y	R/W-0	R/W-0
	—	SWDTPS<4:0>					WDTWINEN	WDTCLR

Legend:		y = Values set from Configuration bits on POR	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Watchdog Timer Enable bit[1,2]

1 = Enables the WDT if it is not enabled by the device configuration
0 = Disable the WDT if it was enabled in software

bit 14-7 **Unimplemented:** Read as '0'

bit 6-2 **SWDTPS<4:0>:** Shadow Copy of Watchdog Timer Postscaler Value from Device Configuration bits

On reset, these bits are set to the values of the WDTPS <4:0> of Configuration bits.

bit 1 **WDTWINEN:** Watchdog Timer Window Enable bit

1 = Enable windowed Watchdog Timer
0 = Disable windowed Watchdog Timer

bit 0 **WDTCLR:** Watchdog Timer Reset bit
1 = Writing a '1' will clear the WDT
0 = Software cannot force this bit to a '0'

Note 1: A read of this bit results in a '1' if the Watchdog Timer is enabled by the device configuration or software.

2: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 16-1: **ICxCON: INPUT CAPTURE 'x' CONTROL REGISTER (CONTINUED)**

bit 2-0   **ICM<2:0>:** Input Capture Mode Select bits

         111 = Interrupt-Only mode (only supported while in Sleep mode or Idle mode)
         110 = Simple Capture Event mode – every edge, specified edge first and every edge thereafter
         101 = Prescaled Capture Event mode – every sixteenth rising edge
         100 = Prescaled Capture Event mode – every fourth rising edge
         011 = Simple Capture Event mode – every rising edge
         010 = Simple Capture Event mode – every falling edge
         001 = Edge Detect mode – every edge (rising and falling)
         000 = Input Capture module is disabled

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

20.1 Control Registers

TABLE 20-1: UART1 THROUGH UART5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6000	U1MODE[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6010	U1STA[1]	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6020	U1TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6030	U1RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6040	U1BRG[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000
6200	U2MODE[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6210	U2STA[1]	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6220	U2TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6230	U2RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6240	U2BRG[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000
6400	U3MODE[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6410	U3STA[1]	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6420	U3TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6430	U3RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 23-1:   AD1CON1: ADC CONTROL REGISTER 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	ON[1]	—	SIDL	—	—	FORM<2:0>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
	SSRC<2:0>			CLRASAM	—	ASAM	SAMP[2]	DONE[3]

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-16　**Unimplemented:** Read as '0'

bit 15　**ON:** ADC Operating Mode bit[1]

　1 = ADC module is operating
　0 = ADC module is not operating

bit 14　**Unimplemented:** Read as '0'

bit 13　**SIDL:** Stop in Idle Mode bit

　1 = Discontinue module operation when device enters Idle mode
　0 = Continue module operation in Idle mode

bit 12-11　**Unimplemented:** Read as '0'

bit 10-8　**FORM<2:0>:** Data Output Format bits

　011 = Signed Fractional 16-bit (DOUT = 0000 0000 0000 0000 sddd dddd dd00 0000)
　010 = Fractional 16-bit (DOUT = 0000 0000 0000 0000 dddd dddd dd00 0000)
　001 = Signed Integer 16-bit (DOUT = 0000 0000 0000 0000 ssss sssd dddd dddd)
　000 = Integer 16-bit (DOUT = 0000 0000 0000 0000 0000 00dd dddd dddd)
　111 = Signed Fractional 32-bit (DOUT = sddd dddd dd00 0000 0000 0000 0000 0000)
　110 = Fractional 32-bit (DOUT = dddd dddd dd00 0000 0000 0000 0000 0000)
　101 = Signed Integer 32-bit (DOUT = ssss ssss ssss ssss ssss sssd dddd dddd)
　100 = Integer 32-bit (DOUT = 0000 0000 0000 0000 0000 00dd dddd dddd)

bit 7-5　**SSRC<2:0>:** Conversion Trigger Source Select bits

　111 = Internal counter ends sampling and starts conversion (auto convert)
　110 = Reserved
　101 = Reserved
　100 = Reserved
　011 = CTMU ends sampling and starts conversion
　010 = Timer 3 period match ends sampling and starts conversion
　001 = Active transition on INT0 pin ends sampling and starts conversion
　000 = Clearing SAMP bit ends sampling and starts conversion

Note 1:　When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2:　If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ 0, this bit is automatically cleared by hardware to end sampling and start conversion.

3:　This bit is automatically set by hardware when ADC is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 23-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)

1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit

1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit[2]

1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit[3]

1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ 0, this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when ADC is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

NOTES:

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24   **EDG1STAT:** Edge 1 Status bit

Indicates the status of Edge 1 and can be written to control edge source

1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 23   **EDG2MOD:** Edge 2 Edge Sampling Select bit

1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22   **EDG2POL:** Edge 2 Polarity Select bit

1 = Edge 2 programmed for a positive edge response
0 = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits

1111 = Reserved
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15   **ON:** ON Enable bit

1 = Module is enabled
0 = Module is disabled

bit 14   **Unimplemented:** Read as '0'

bit 13   **CTMUSIDL:** Stop in Idle Mode bit

1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12   **TGEN:** Time Generation Enable bit[1]

1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11   **EDGEN:** Edge Enable bit

1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

   2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

   3: Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0 "Electrical Characteristics"** for current values.

   4: This bit setting is not available for the CTMU temperature diode.

27.4.1 CONTROLLING CONFIGURATION CHANGES

Because peripherals can be disabled during run time, some restrictions on disabling peripherals are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to enabled or disabled peripherals:

• Control register lock sequence
• Configuration bit select lock

27.4.1.1 Control Register Lock

Under normal operation, writes to the PMDx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the PMDLOCK Configuration bit (CFGCON<12>). Setting PMDLOCK prevents writes to the control registers; clearing PMDLOCK allows writes.

To set or clear PMDLOCK, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

27.4.1.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the PMDx registers. The PMDL1WAY Configuration bit (DEVCFG3<28>) blocks the PMDLOCK bit from being cleared after it has been set once. If PMDLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable PMD functionality is to perform a device Reset.

TABLE 31-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I$_{PD}$)

DC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp	
Param. No.	Typ.[2]	Max.	Units	Conditions	
PIC32MX330 Devices Only					
Power-Down Current (I$_{PD}$) (Note 1)					
DC40k	20	55	μA	-40°C	Base Power-Down Current
DC40l	38	55	μA	+25°C	
DC40n	128	167	μA	+85°C	
DC40m	261	419	μA	+105ºC	
PIC32MX430 Devices Only					
Power-Down Current (I$_{PD}$) (Note 1)					
DC40k	12	28	μA	-40°C	Base Power-Down Current
DC40l	21	28	μA	+25°C	
DC40n	128	167	μA	+85°C	
DC40m	261	419	μA	+105ºC	
PIC32MX350F128 Devices Only					
Power-Down Current (I$_{PD}$) (Note 1)					
DC40k	31	70	μA	-40°C	Base Power-Down Current
DC40l	45	70	μA	+25°C	
DC40n	175	280	μA	+85°C	
DC40m	415	600	μA	+105ºC	
PIC32MX450F128 Devices Only					
Power-Down Current (I$_{PD}$) (Note 1)					
DC40k	19	35	μA	-40°C	Base Power-Down Current
DC40l	28	35	μA	+25°C	
DC40n	175	280	μA	+85°C	
DC40m	415	600	μA	+105ºC	

Note 1: The test conditions for I$_{PD}$ measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled
- Voltage regulator is off during Sleep mode (VREGS bit in the RCON register = 0)

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I$_{PD}$ current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: 120 MHz commercial devices only (0ºC to +70ºC).

PIC32MX330/350/370/430/450/470

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symb.	Characteristics	Min.	Typ.[1]	Max.	Units	Conditions
		Input Leakage Current (Note 3)					
DI50	IIL	I/O Ports	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$[2]	—	—	±1	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes
DI60a	IICL	**Input Low Injection Current**	0	—	-5[7,10]	mA	Pins with Analog functions. Exceptions: [N/A] = 0 mA max
							Digital 5V tolerant designated pins. Exceptions: [N/A] = 0 mA max
							Digital non-5V tolerant designated pins. Exceptions: [N/A] = 0 mA max

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Device Pin Tables"** section for the 5V tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX330/350/370/430/450/470 AC characteristics and timing parameters.

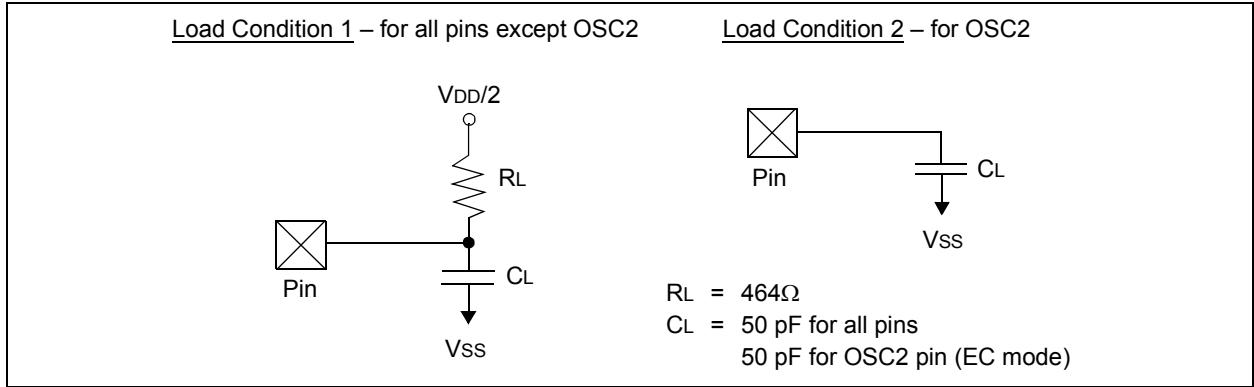**FIGURE 31-1:** **LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS**

Load Condition 1 – for all pins except OSC2   Load Condition 2 – for OSC2

R_L = 464Ω
C_L = 50 pF for all pins
      50 pF for OSC2 pin (EC mode)

TABLE 31-17: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C $\leq$ T$_A$ $\leq$ +70°C for Commercial -40°C $\leq$ T$_A$ $\leq$ +85°C for Industrial -40°C $\leq$ T$_A$ $\leq$ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical[1]	Max.	Units	Conditions
DO50	C_{OSCO}	OSC2 pin	—	—	15	pF	In XT and HS modes when an external crystal is used to drive OSC1
DO56	C_{IO}	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	C_B	SCLx, SDAx	—	—	400	pF	In I^{2}C mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-2: **EXTERNAL CLOCK TIMING**
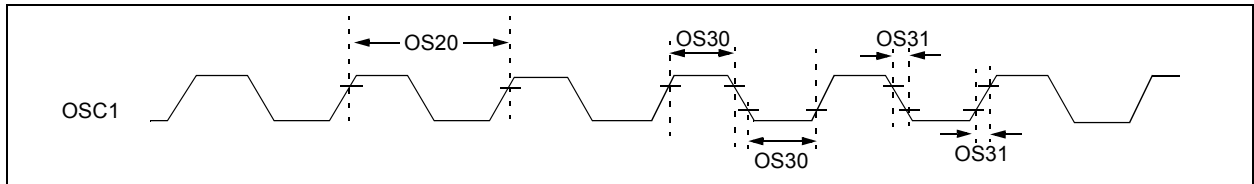
**TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS** (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C $\le$ TA $\le$ +70°C for Commercial -40°C $\le$ TA $\le$ +85°C for Industrial -40°C $\le$ TA $\le$ +105°C for V-temp				
Param. No.	Symbol	Characteristics[1]	Min.	Typ.[2]	Max.	Units	Conditions
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	TSCK + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging
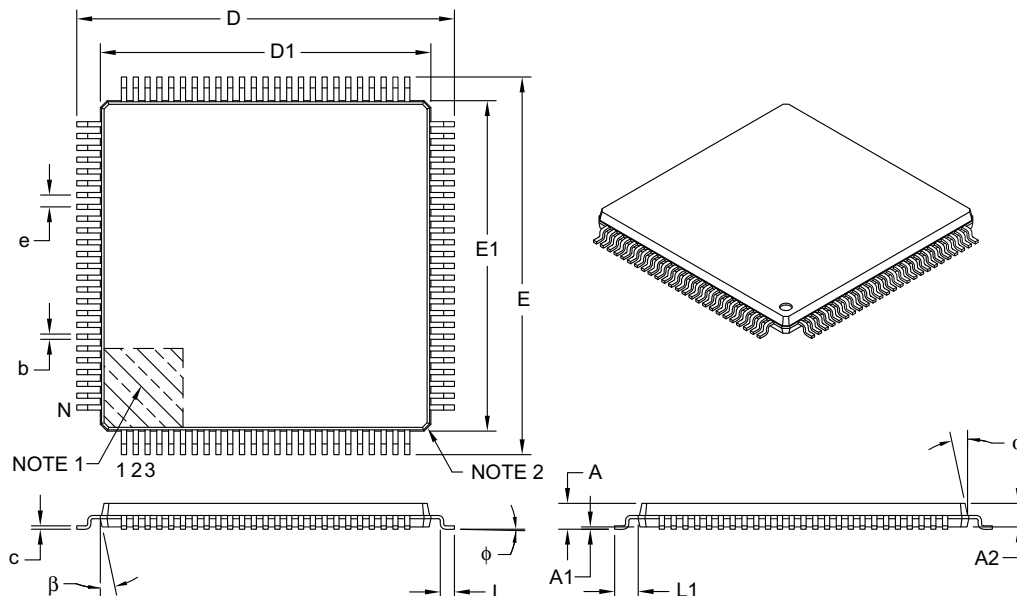
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B